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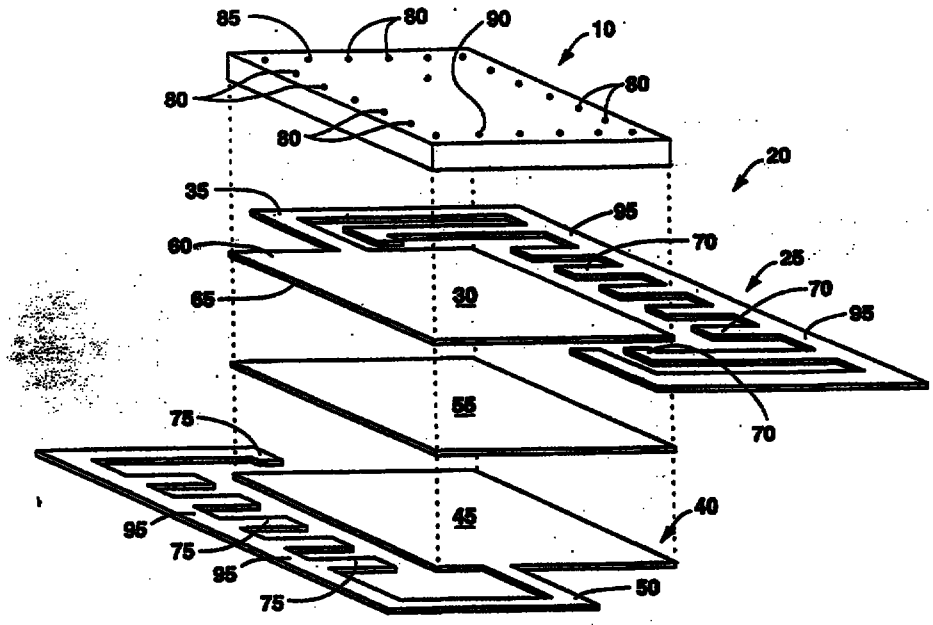
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(54) Title: MULTI-LAYER LEAD FRAME FOR A SEMICONDUCTOR DEVICE



(57) Abstract

A multi-layer lead frame (20) for decoupling a power supply to a semiconductor die (10) includes overlaying first (25) and second lead frame (40) bodies having an insulator (55) disposed therebetween and at least one main lead finger (35, 50) extending from each body (25, 40). The bodies (25, 40) act as a capacitor to decouple the power supply to the die (10). One of the bodies and respective finger provides one of power supply and ground connections for wire bonding with the die (10), and the other of the bodies provides the other of power supply and ground connections for wire bonding with the die (10). The first body (25) includes a die paddle (30) for supporting the die (10), and the second body (40) includes a plate (45) for overlaying the paddle (30) with the insulator (55) disposed between the paddle (30) and plate (45), thereby providing an electrical decoupling effect therebetween upon supplying power and ground connections, respectively.

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